

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	600	imaging and (adhesive with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:34
S2	2	S1 and (restricting or impeding) with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:13
S3	0	imaging and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:08
S4	8	semiconductor and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:12
S5	0	imaging and (transparent adj lens) and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:16
S6	0	S4 and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:11
S7	368	S1 and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:18

S8	0	S7 and semiconductor and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:12
S9	0	S7 and (restricting or impeding) with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 14:31
S10	4	S7 and groove with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:33
S11	4	S7 and (groove with adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:14
S12	0	(transparent adj lens) and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:18
S13	0	(transparent with lens) and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:17
S14	0	(transparent with cover) and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:17
S15	0	(transparent with layer) and ((adhesive adj flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:17

S16	0	(transparent adj lens) and ((adhesive with flow) with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:18
S17	368	S1 and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:25
S18	51	S17 and (transparent with (cover or lens))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 11:26
S19	12	S18 and (adhesive with (groove or trench))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/16 12:32
S20	0	S19 and ((groove or trench) with curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/16 12:35
S21	0	S1 and ((groove or trench) with curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/16 12:35
S22	0	imaging and (adhesive with (groove or trench) with curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 12:37
S23	6	transparent and (adhesive with (groove or trench) with curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/16 12:37

S24	2	("6566745").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/15 19:01
S25	677	imaging and (adhesive with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 14:28
S26	404	S25 and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 14:43
S27	4	S26 and groove with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 14:28
S28	31	((groove or trench) and (restricting or impeding)) with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:16
S29	2	S28 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 14:33
S30	677	imaging and (adhesive with (dam or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:10
S31	203	S30 and die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 15:43

S32	44	S31 and (die with adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 15:43
S33	9	imaging and (adhesive with trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 15:50
S34	415	(transparent with (cap or lid or cover or electrode) with (groove or trench or recess or gap or opening) with (adhesive or glue))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:28
S35	8	S34 and imaging	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:41
S36	260	(transparent with (lid or cover) with (groove or trench or recess or gap or opening) with (adhesive or glue))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:29
S37	46	(transparent with (lid or cover) with (groove or trench) with (adhesive))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:40
S38	0	S37 and imaging	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:30
S39	24	(transparent with (lid or cover)) and (adhesive with flow with (groove or trench))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 15:44

S40	2	S39 and imaging	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 14:42
S41	15	imaging and (adhesive with (dam or barrier)) and (transparent with lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:33
S42	0	(adhesive with barrier with trench) and (transparent with lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:33
S43	0	(adhesive with barrier with trench) and (transparent with cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:34
S44	0	(adhesive with flow with trench) and (transparent with cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:34
S45	0	(adhesive with flow with trench) and (transparent with lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:34
S46	643	257/434.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:38
S47	2	S46 and (transparent with groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:42

S48	5	S46 and (cover with groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:45
S49	1	((transparent with (lid or cover)) and (encapsulant with flow with (groove or trench)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 15:44
S50	11	encapsulant with (lid or cover) with (trench or groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/04 15:46
S51	0	((die or wafer) with (trench with adhesive with (restricts or restricting)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:15
S52	0	((die or wafer or chip or substrate) with (trench with adhesive with (restricts or restricting)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:15
S53	2	((die or wafer or chip or substrate) with (trench with adhesive with (restricts or restricting or restriction)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:15
S54	12	((groove or trench) with (wafer or chip or die or substrate)) and ((restricting or impeding) with (adhesive or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:42
S55	18	((groove or trench or dam) with (wafer or chip or die or substrate)) and ((restricting or impeding) with (adhesive or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:35

S56	1417	257/622.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:32
S57	1	S56 and (groove with adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:40
S58	1	S56 and (imaging and (adhesive with (dam or groove or trench or barrier)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:34
S59	40	((groove or trench or dam or barrier) with (wafer or chip or die or substrate)) and ((restricting or impeding) with (adhesive or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:39
S60	5	((groove or trench or dam or barrier) with (wafer or chip or die or substrate)) and ((restricting or impeding) with flow with (adhesive or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:40
S61	1	groove with (adhesive or epoxy) with flow with (restrict or restricting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:41
S62	3	((groove or trench) with (wafer or chip or die or substrate)) and (((restricting or impeding) with flow) with (adhesive or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:43
S63	2	"6891236"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 18:10

S64	1	"5414300".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:27
S65	1	"6034429".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:28
S66	1	"6034429".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:28
S67	1	"5414300".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:28
S68	1	"5336931".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:29
S69	1	"5278429".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:29
S70	1	"5336931".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:29
S71	1	"5436203".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:30
S72	1	"4159221".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:31
S73	1	"4530152".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:31
S74	1	"4890383".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:31
S75	1	"5001829".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:31
S76	1	"5043004".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:32
S77	1	"5102829".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:32
S78	1	"5105260".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:32
S79	1	"5126818".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:32
S80	1	"5192681".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:32
S81	1	"5230759".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:33

S82	1	"5241133".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:33
S83	1	"5250470".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:33
S84	1	"5278429".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:33
S85	1	"5336931".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:34
S86	1	"5414300".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:34
S87	1	"5422615".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:34
S88	1	"5436203".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:34
S89	1	"5474957".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:35
S90	1	"5578525".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:35
S91	1	"5593926".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:35
S92	1	"5641713".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:36
S93	1	"5742007".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:36
S94	1	"5776798".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:36
S95	1	"5801074".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:36
S96	1	"5950074".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:36
S97	1	"6034429".PN.	USPAT; USOCR	OR	ON	2007/01/18 11:38
S98	0	"257E23.181"	USPAT; USOCR	OR	ON	2007/01/18 11:38
S99	6	"257/E23.181"	USPAT; USOCR	OR	ON	2007/01/18 11:41

S100	8	"257/E23.193"	USPAT; USOCR	OR	ON	2007/01/18 11:45
S101	102838	257/434, "431", "432".ccls.	USPAT; USOCR	OR	ON	2007/01/18 11:47
S102	1840	257/434,431,432".ccls.	USPAT; USOCR	OR	ON	2007/01/18 11:50
S103	7153	257/434,431,432,678,680,704,783,787,710,684,687.ccls.	USPAT; USOCR	OR	ON	2007/01/18 11:49
S104	29	trench with encapsulant	USPAT; USOCR	OR	ON	2007/01/18 11:50
S105	1	"6011301".PN.	USPAT; USOCR	OR	ON	2007/08/31 23:19
S106	1	"6214643".PN.	USPAT; USOCR	OR	ON	2007/08/31 23:20
S107	1	"6420204".PN.	USPAT; USOCR	OR	ON	2007/08/31 23:20
S108	1	"6509635".PN.	USPAT; USOCR	OR	ON	2007/08/31 23:21
S109	1	"6566745".PN.	USPAT; USOCR	OR	ON	2007/08/31 23:21
S110	1	"6667439".PN.	USPAT; USOCR	OR	ON	2007/08/31 23:22
S111	1	"6744109".PN.	USPAT; USOCR	OR	ON	2007/08/31 23:23
S112	1	"20010014486".PN.	US-PGPUB	OR	ON	2007/08/31 23:24
S113	1	"20040262781".PN.	US-PGPUB	OR	ON	2007/08/31 23:24
S114	1	"20050051885".PN.	US-PGPUB	OR	ON	2007/08/31 23:34
S115	0	"7064452"	US-PGPUB	OR	ON	2007/09/01 00:00
S116	3	("20010014486" "20040262781" "20050051885" "6011301" "6214643" "6420204" "6509635" "6566745" "6667439" "6744109").PN.	US-PGPUB	OR	ON	2007/09/01 00:00

S117	41	(encapsulant or adhesive) with (chip or die or substrate) with (semiconductor or imag\$3) with (trench or groove) with (dam or restrict\$3 or barrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 15:52
S118	91	(encapsulant or adhesive) with (chip or die or substrate) with (trench or groove) with (dam or restrict\$3 or barrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 15:12
S119	50	S118 not S117	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 14:53
S120	523	(encapsulant or adhesive) and ((chip or die or substrate) with (trench or groove) with (dam or restrict\$3 or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 15:13
S121	205	(encapsulant or adhesive) and ((chip or die or substrate) with (trench or groove) with (dam or restrict\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 15:14
S122	233	(encapsulant or adhesive or epoxy) and ((chip or die or substrate) with (trench or groove) with (dam or restrict\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 15:39
S123	5	(encapsulant or adhesive or epoxy) and ((chip or die or substrate) with (cap or lid) with (trench or groove) with (dam or restrict\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 15:45
S124	25210	(encapsulant or adhesive or epoxy) and ((chip or die or substrate) with (trench or groove))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 15:47

S125	178	(encapsulant or adhesive or epoxy) and ((chip or die or substrate) with (trench or groove) with restrict\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 15:47
S126	0	(semiconductor with (die or chip) with (groove or trench) with restrict\$3 with flow with (encapsulant or adhesive or epoxy or sealant))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 15:54
S127	6	((die or chip) with (groove or trench) with restrict\$3 with flow with (encapsulant or adhesive or epoxy or sealant))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 16:33
S128	1	(die or chip) with (groove or trench) with impeding with flow with (encapsulant or adhesive or epoxy or sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 16:39
S129	1331	(die or chip) with (groove or trench) with (encapsulant or adhesive or epoxy or sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 19:56
S130	33	"6184064"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 16:47
S131	7	(die or chip) with (groove or trench) with (encapsulant or adhesive or epoxy or sealant) with restrict\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 19:28
S132	20	"6225695"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 19:38

S133	205	S129 and restrict\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 20:05
S134	44	S129 and (restrict\$3 with flow\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/02 20:06
S135	4151	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/01 22:09
S136	816	257/434.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/01 22:09
S137	1531	257/622.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/01 22:10
S138	918	257/680.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/01 22:11
S139	1330	257/783.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/01 22:12
S140	910	257/687.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/01 22:13

S141	546	257/710.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/01 22:14
S142	9453	S135 or S136 or S137 or S138 or S139 or S140 or S141	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/01 22:14
S143	2	S142 and ((adhesive adj flow) with (trench or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/01 22:15
S144	0	imaging with die with surface with transparent with adhesively with flow with restriction with trench with below with surface.clms.	US-PGPUB	OR	OFF	2008/09/01 22:18

9/2/08 11:13:18 AM

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